

Part Number: XZMDKDGCBD56W

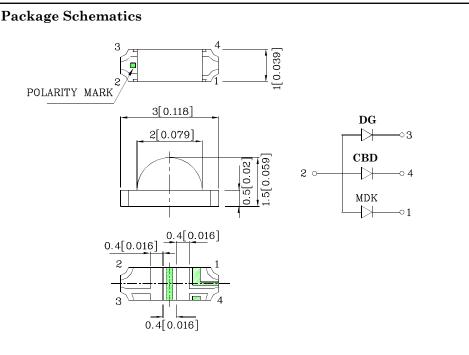
3.0x1.0mm RIGHT ANGLE SMD CHIP LED LAMP

Features

- \bullet 3.0 X 1.0 X 1.5mm right angle SMD LED
- Ideal for indication on hand held products
- Low current operation
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES





1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		MDK (AlGaI nP)	DG (InGa N)	CBD (InG aN)	Unit
Reverse Voltage	V_{R}	5	5	5	V
Forward Current	$I_{\rm F}$	30	25	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	185	150	150	mA
Power Dissipation	\mathbf{P}_{D}	75	102.5	120	mW
Electrostatic Discharge Threshold (HBM)		-	450	250	V
Operating Temperature	$T_{\rm A}$	-40 ~ +85			°C
Storage Temperature	Tstg				U

Operating Characteristics (T _A =25°C)		MDK (AlGaIn P)	DG (InGa N)	CBD (InGa N)	Unit
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	1.95	3.3	3.3	v
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	4.1	4.0	V
Reverse Current (Max.) (V _R =5V)	$\mathbf{I}_{\mathbf{R}}$	10	50	50	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	645*	515*	460*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =20mA)	λD	630*	525*	465*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle \lambda$	28	30	25	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	35	45	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* λΡ nm	Viewing Angle 20 1/2
				min.	typ.		
XZMDKDGCBD56W	Red	AlGaInP	Water Clear	55*	79*	645*	120°
	Green	InGaN		200*	297*	515*	
	Blue	InGaN		40*	69*	468*	

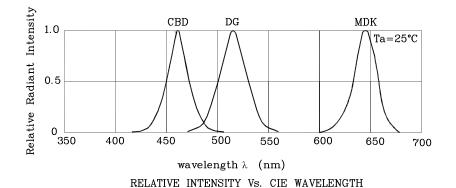
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

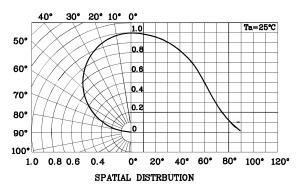
Jan 20, 2014

XDSB6309 V3-Z Layout: Maggie L.

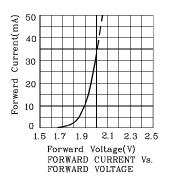


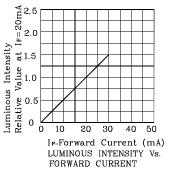
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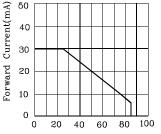




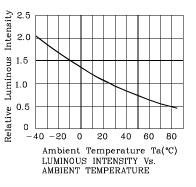
♦ MDK



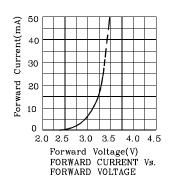


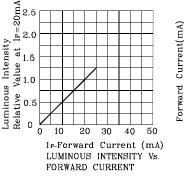


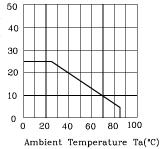
Ambient Temperature Ta(°C) FORWARD CURRENT DERATING CURVE

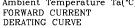


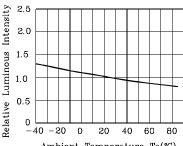
♦ DG





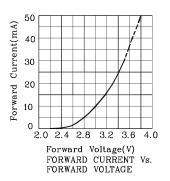


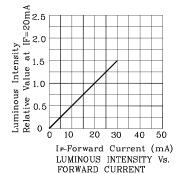


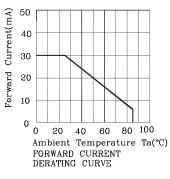


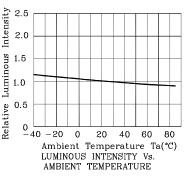


* CBD









XDSB6309 V3-Z Layout: Maggie L.



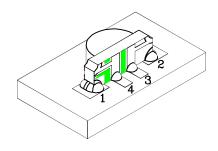
***** LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

The device has a single mounting surface. The device must be mounted according to the specifications.

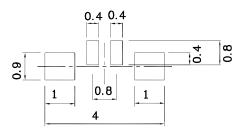
300 (°C) 10 8 250 4°C/s 200 150~180°C 4°C/s max 150 Temperature 100 50 100 150 200 250 300 (sec) Tin Notes: 1. Maximum soldering temperature should not exceed 260°C 2. Recommended reflow temperature: 145°C-260°C З. Do not put stress to the epoxy resin during

high temperatures conditions



Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

Reel Dimension



Tape Specification (Units : mm)

TAPE 12[.472]±0.5 **75±0.1** 4.0±0.1 0.2±0.1 4.0±0.1 ø1.5±0.1 2.0±0.1 R6.5[.256]±0,1 18[.709]±0.2 -78[7.008]±1 .25±0.1 362 5±0.05 **8.0±0.3** 3 C 4 c R36[1.417] 2 9[.354]±0.2

Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

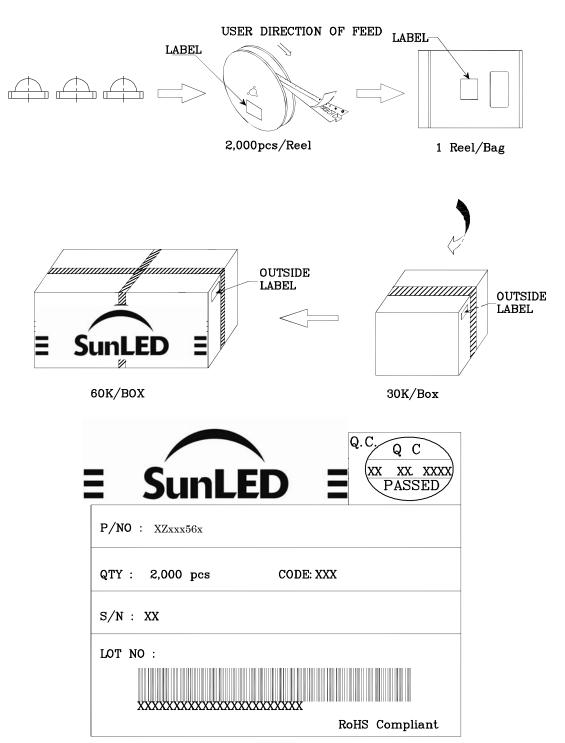
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$